

Also published as:

EP0820155 (A)

US6060960 (A)

EP0820155 (A:

EP0820155 (A:

H01P1/213; H01P1/15; H04B1/44; H04B1/48;
H04B1/52; H03H9/05; H01P1/20; H01P1/10; H04B1/44;
H04B1/50; H03H9/05; (IPC-7); H04B1/44; H01P1/213

H01P1/15; H04B1/48; H04B1/52

JP19960187422 19960717

JP19960187422 19960717

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PROBLEM TO BE SOLVED: To reduce the size, weight and cost by mounting plural dielectric layers constituting a high-frequency switch to a laminated multilayered substrate and integrating the high-frequency switch and a SAW filter to reduce the mount area of the high-frequency switch and the SAW filter within a printed wiring board. **SOLUTION:** Duplexer 1 mounts the SAW filter F2 on the multilayered substrate laminating plural dielectric layers constituting the high-frequency switch SW, additionally incorporates and integrates an LC filter. The duplexer 1 includes a multilayered substrate consisting of a low-temperature backed ceramic substrate mainly composed of barium oxide, aluminum oxide, silica, etc. Thereby the mount area of the high-frequency switch and the SAW filter within the printed wiring board is reduced to realize a small size and a light weight. In addition, as the high-frequency switch and the filter can simultaneously be designed, the high-frequency switch and the filter can be designed by giving impedance matching to unecessitate a matching circuit.

